



## Features

- 1400 Watts Peak Pulse Power per Line ( $t_p = 8/20\mu s$ )
- Protects one I/O or power line
- Low Clamping Voltage
- Working Voltage: 15V
- Low Leakage Current

## IEC Compatibility (EN61000-4)

- IEC 61000-4-2 (ESD)  $\pm 30kV$  (air),  $\pm 30kV$  (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 50A (8/20 $\mu s$ )

## Mechanical Characteristics

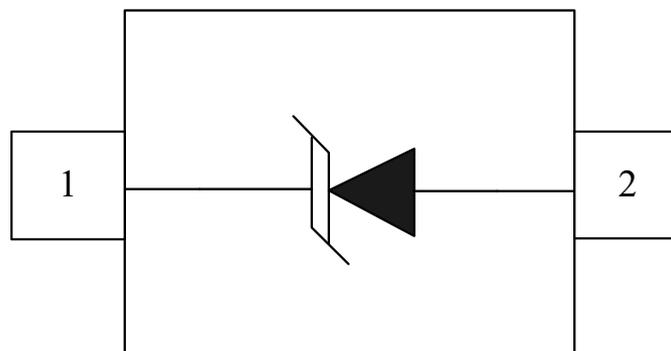
- SOD-323F package
- Marking: Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant

## Applications

- Laptop Computers
- Cellular Phones
- Digital Cameras
- Personal Digital Assistants (PDAs)



## Schematic & PIN Configuration

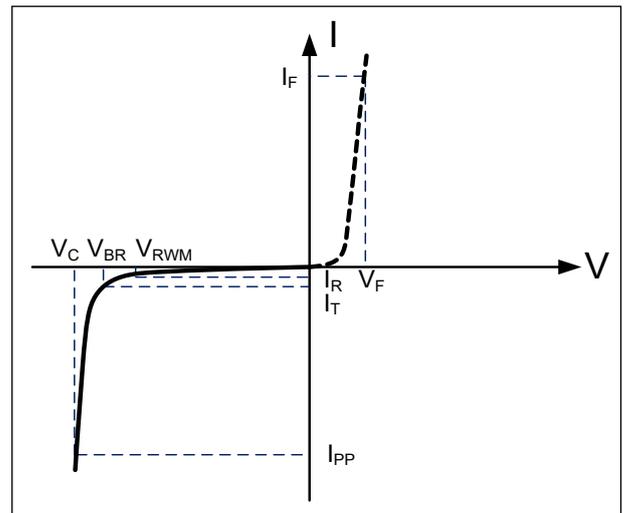


SOD-323F (Top View)

<b>Absolute Maximum Rating</b>			
Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{PP}$	1400	Watts
Peak Pulse Current ( $t_p = 8/20\mu s$ )	$I_{PP}$	50	A
Operating Temperature	$T_J$	-55 to +125	$^{\circ}C$
Storage Temperature	$T_{STG}$	-55 to +150	$^{\circ}C$

## Electrical Parameters (T=25 $^{\circ}C$ )

Symbol	Parameter
$I_{PP}$	Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Reverse Stand-Off Voltage
$I_R$	Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$



## Electrical Characteristics

<b>DW15D3HP-S</b>						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{RWM}$				15	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T = 1mA$	16		20	V
Forward Voltage	$V_F$	$I_F = 10mA$	0.5		1.0	V
Reverse Leakage Current	$I_R$	$V_{RWM} = 15V, T = 25^{\circ}C$			100	nA
Clamping Voltage	$V_C$	$I_{PP} = 50A, t_p = 8/20\mu s$		25	28	V
ESD Clamping Voltage <sup>1</sup>	$V_C$	$I_{PP} = 4A, t_p = 0.2/100ns$ (TLP)		17.4		V
ESD Clamping Voltage <sup>1</sup>	$V_C$	$I_{PP} = 16A, t_p = 0.2/100ns$ (TLP)		18.6		V
Dynamic Resistance <sup>1,2</sup>	$R_{DYN}$	TLP=0.2/100ns		0.1		$\Omega$
Junction Capacitance	$C_j$	$V_R = 0V, f = 1MHz$		320	350	pF

Notes : 1、TLP Setting :  $t_p = 100ns, t_r = 0.2ns, I_{TLP}$  and  $V_{TLP}$  sample window:  $t_1 = 70ns$  to  $t_2 = 90ns$ .

2、Dynamic resistance calculated from  $I_{PP} = 4A$  to  $I_{PP} = 16A$  using "Best Fit".

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## Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

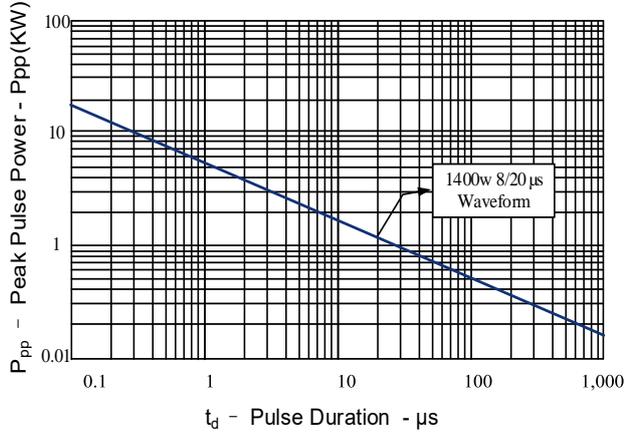


Figure 2: Power Derating Curve

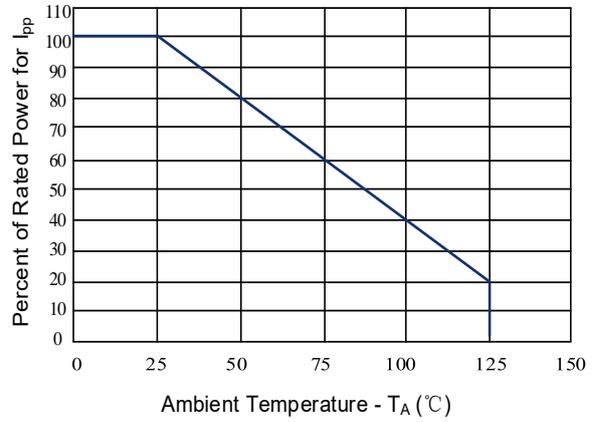


Figure 3: Clamping Voltage vs. Peak Pulse Current

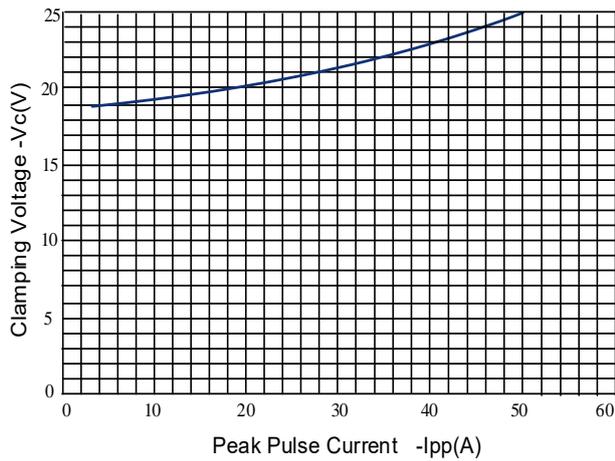


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

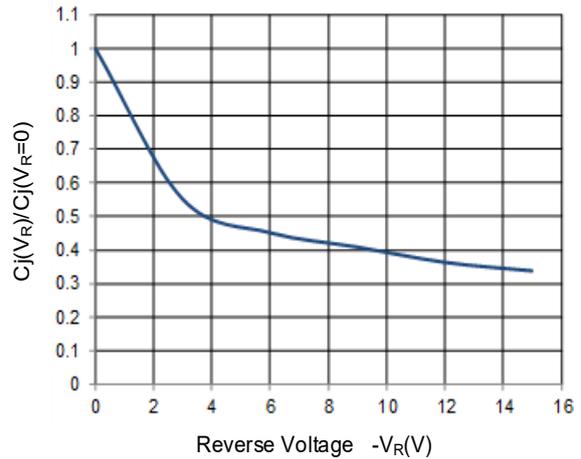


Figure 5: Pulse Waveform

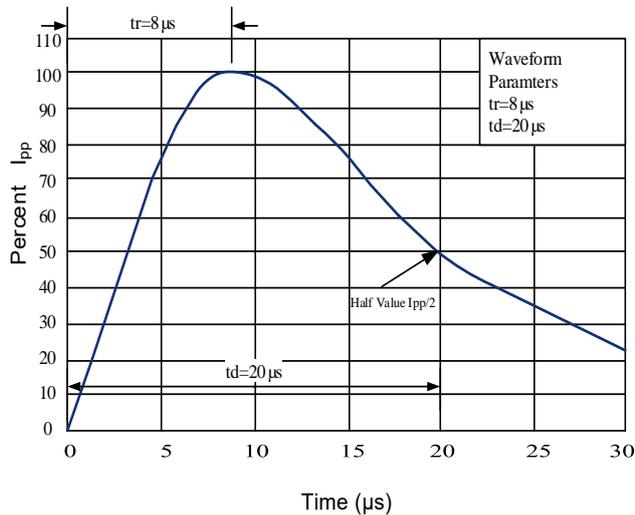
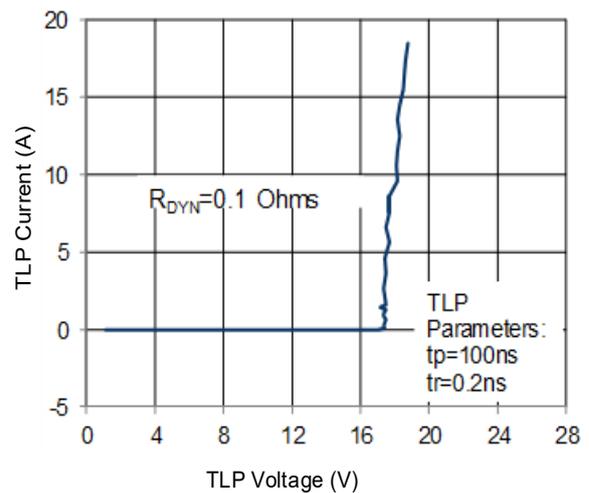


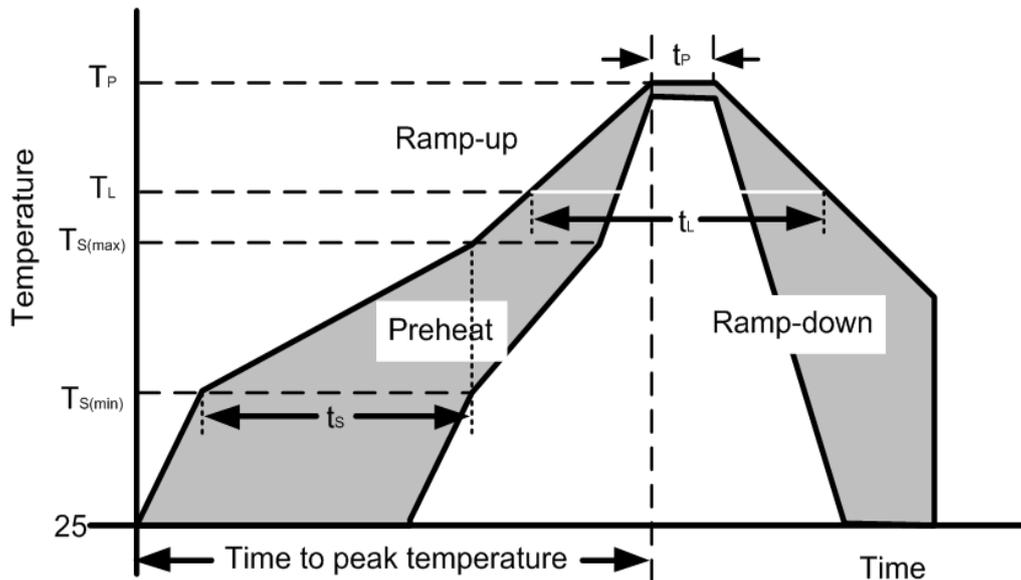
Figure 6: TLP Positive I-V Curve





## Soldering Parameters

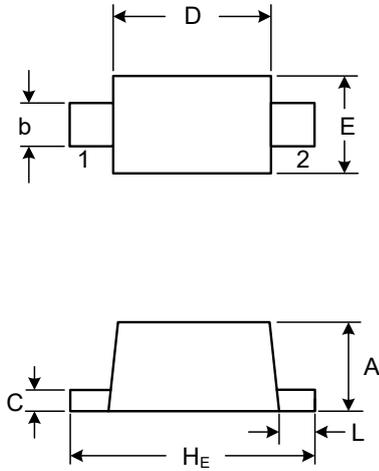
Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ( $T_{S(min)}$ )	150°C
	Temperature Max ( $T_{S(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 190 secs
Average ramp up rate (Liquidus Temp) ( $T_L$ ) to peak		5°C/second max
$T_{S(max)}$ to $T_L$ —Ramp-up Rate		5°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_P$ )		260+0/-5 °C
Time within actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature ( $T_P$ )		8 minutes Max.
Do not exceed		280°C



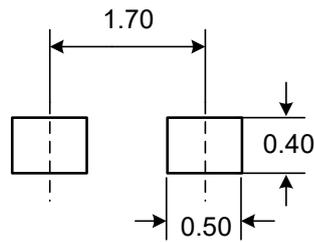
## Outline Drawing – SOD-323F

SYMBOL	MILLIMETERS		
	MIN	TYP	MAX
A	0.60	0.65	0.75
b	0.25	0.30	0.40
C	0.06	0.13	0.21
D	1.60	1.70	1.80
E	1.15	1.25	1.35
H <sub>E</sub>	2.30	2.50	2.70
L	0.30	0.40	0.50

### PACKAGE OUTLINE



SOD-323F



DIMENSIONS: MILLIMETERS

**Notes:**  
Controlling Dimension: Millimeter.

## Marking Codes

Part Number	Marking Code
DW15D3HP-S	

## Package Information

Qty: 3k/Reel